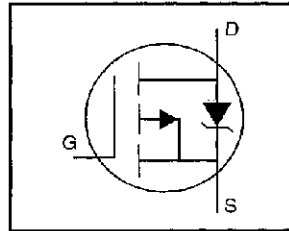


# IRF9Z14PbF

## HEXFET® Power MOSFET

- Dynamic  $dv/dt$  Rating
- Repetitive Avalanche Rated
- P-Channel
- 175°C Operating Temperature
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Lead-Free

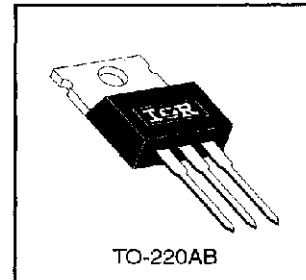


$V_{DSS} = -60V$
$R_{DS(on)} = 0.50\Omega$
$I_D = -6.7A$

### Description

Third Generation HEXFETs from International Rectifier provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 watts. The low thermal resistance and low package cost of the TO-220 contribute to its wide acceptance throughout the industry.



### Absolute Maximum Ratings

	Parameter	Max.	Units
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10 V$	-6.7	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ -10 V$	-4.7	
$I_{DM}$	Pulsed Drain Current ①	-27	
$P_D @ T_C = 25^\circ C$	Power Dissipation	43	W
	Linear Derating Factor	0.29	W/°C
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$E_{AS}$	Single Pulse Avalanche Energy ②	140	mJ
$I_{AR}$	Avalanche Current ①	-6.7	A
$E_{AR}$	Repetitive Avalanche Energy ①	4.3	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ ③	-4.5	V/ns
$T_J$	Operating Junction and Storage Temperature Range	-55 to +175	°C
$T_{STG}$	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	
	Mounting Torque, 6-32 or M3 screw	10 lbf·in (1.1 N·m)	

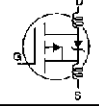
### Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	—	3.5	°C/W
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	—	0.50	—	
$R_{\theta JA}$	Junction-to-Ambient	—	—	62	

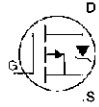
# IRF9Z14PbF

International  
 Rectifier

## Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

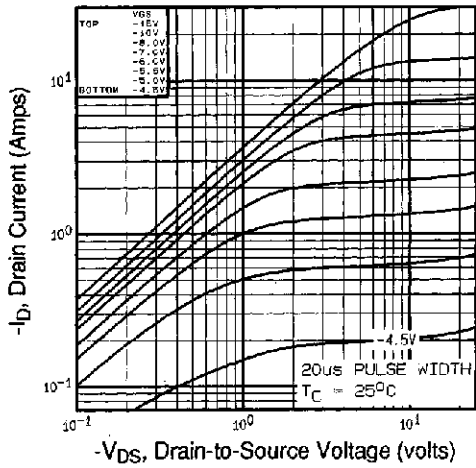
	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	-60	—	—	V	$V_{GS}=0V, I_D=-250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	-0.060	—	V/°C	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	—	0.50	$\Omega$	$V_{GS}=-10V, I_D=-4.0A$ ④
$V_{GS(th)}$	Gate Threshold Voltage	-2.0	—	-4.0	V	$V_{DS}=V_{GS}, I_D=-250\mu A$
$g_{fs}$	Forward Transconductance	1.4	—	—	S	$V_{DS}=-25V, I_D=-4.0A$ ④
$I_{DSS}$	Drain-to-Source Leakage Current	—	—	-100	$\mu A$	$V_{DS}=-60V, V_{GS}=0V$
		—	—	-500		$V_{DS}=-48V, V_{GS}=0V, T_J=150^\circ\text{C}$
$I_{GSS}$	Gate-to-Source Forward Leakage	—	—	-100	nA	$V_{GS}=20V$
	Gate-to-Source Reverse Leakage	—	—	100		$V_{GS}=20V$
$Q_g$	Total Gate Charge	—	—	12	nC	$I_D=-6.7A$
$Q_{gs}$	Gate-to-Source Charge	—	—	3.8		$V_{DS}=-48V$
$Q_{gd}$	Gate-to-Drain ("Miller") Charge	—	—	5.1		$V_{GS}=-10V$ See Fig. 6 and 13 ④
$t_{d(on)}$	Turn-On Delay Time	—	11	—	ns	$V_{DD}=-30V$
$t_r$	Rise Time	—	63	—		$I_D=-6.7A$
$t_{d(off)}$	Turn-Off Delay Time	—	10	—		$R_G=24\Omega$
$t_f$	Fall Time	—	31	—		$R_D=4.0\Omega$ See Figure 10 ④
$L_D$	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6 mm (0.25in.) from package and center of die contact 
$L_S$	Internal Source Inductance	—	7.5	—		
$C_{ISS}$	Input Capacitance	—	270	—	pF	$V_{GS}=0V$
$C_{OSS}$	Output Capacitance	—	170	—		$V_{DS}=-25V$
$C_{RSS}$	Reverse Transfer Capacitance	—	31	—		$f=1.0\text{MHz}$ See Figure 5

## Source-Drain Ratings and Characteristics

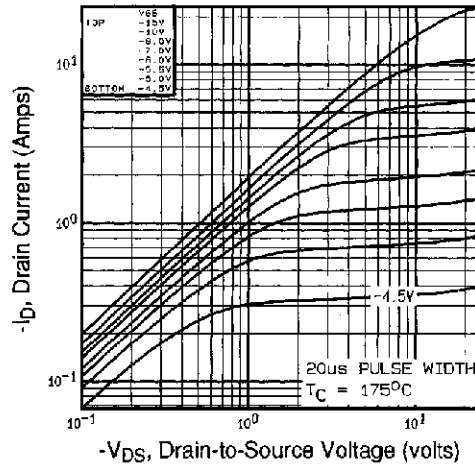
	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$I_S$	Continuous Source Current (Body Diode)	—	—	-6.7	A	MOSFET symbol showing the integral reverse p-n junction diode. 
$I_{SM}$	Pulsed Source Current (Body Diode) ①	—	—	-27		
$V_{SD}$	Diode Forward Voltage	—	—	-5.5	V	$T_J=25^\circ\text{C}, I_S=-6.7A, V_{GS}=0V$ ③
$t_{rr}$	Reverse Recovery Time	—	80	160	ns	$T_J=25^\circ\text{C}, I_F=-6.7A$
$Q_{rr}$	Reverse Recovery Charge	—	0.096	0.19	$\mu C$	$di/dt=100A/\mu s$ ④
$t_{on}$	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S+L_D$ )				

### Notes:

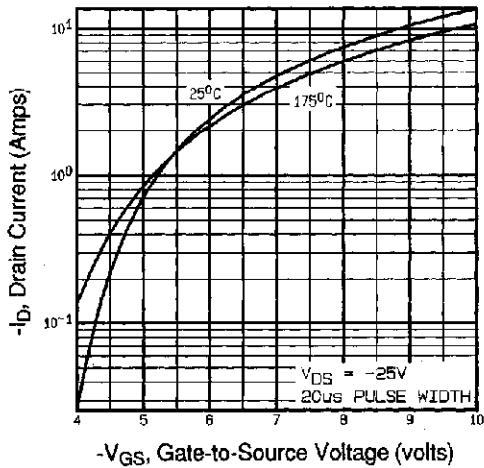
- ① Repetitive rating; pulse width limited by max. junction temperature (See Figure 11)
- ②  $V_{DD}=-25V$ , starting  $T_J=25^\circ\text{C}$ ,  $L=3.6\text{mH}$ ,  $R_G=25\Omega$ ,  $I_{AS}=-6.7A$  (See Figure 12)
- ③  $I_{SD}\leq-6.7A$ ,  $di/dt\leq 90A/\mu s$ ,  $V_{DD}\leq V_{(BR)DSS}$ ,  $T_J\leq 175^\circ\text{C}$
- ④ Pulse width  $\leq 300\mu s$ ; duty cycle  $\leq 2\%$ .



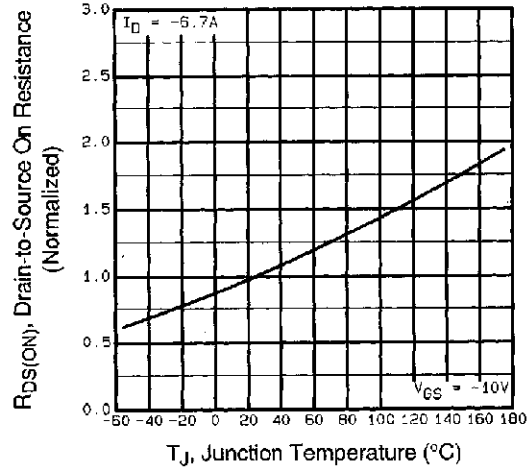
**Fig 1.** Typical Output Characteristics,  
 $T_C=25^\circ\text{C}$



**Fig 2.** Typical Output Characteristics,  
 $T_C=175^\circ\text{C}$

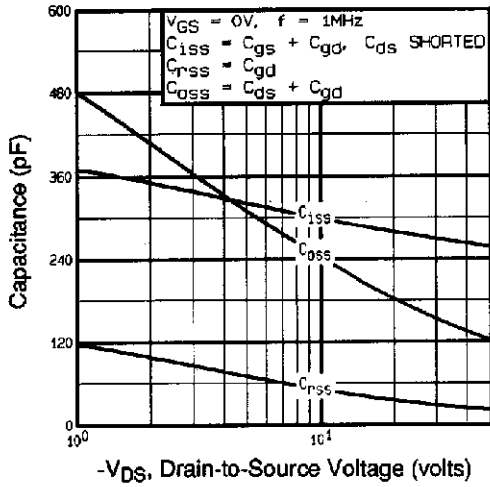


**Fig 3.** Typical Transfer Characteristics

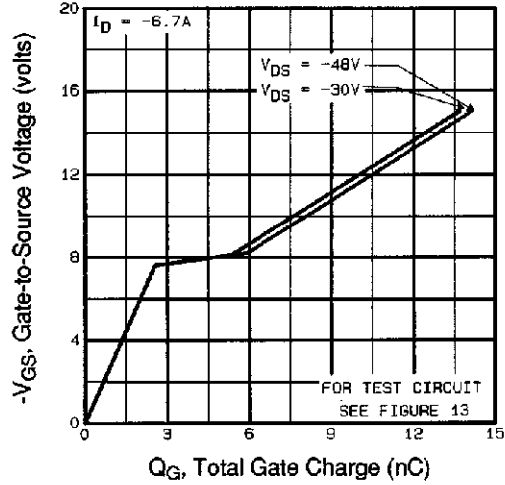


**Fig 4.** Normalized On-Resistance  
Vs. Temperature

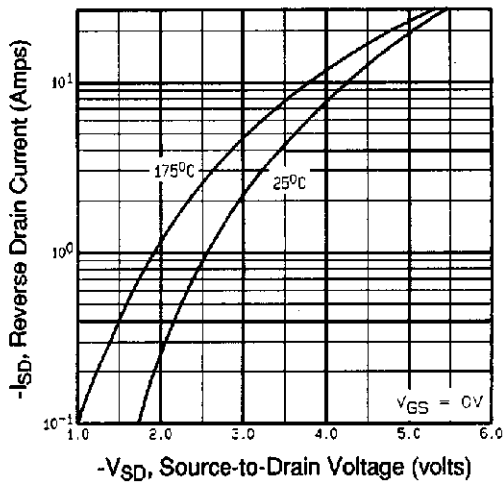
# IRF9Z14PbF



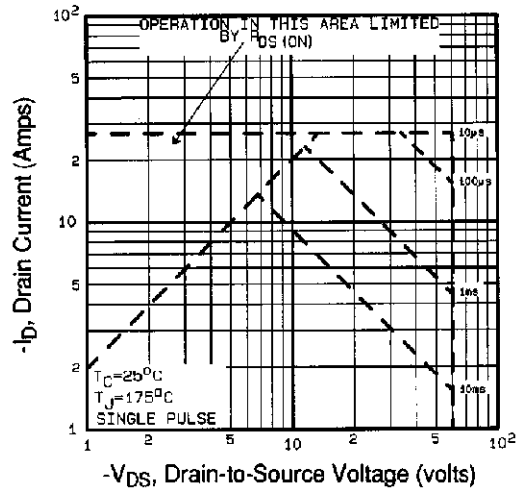
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



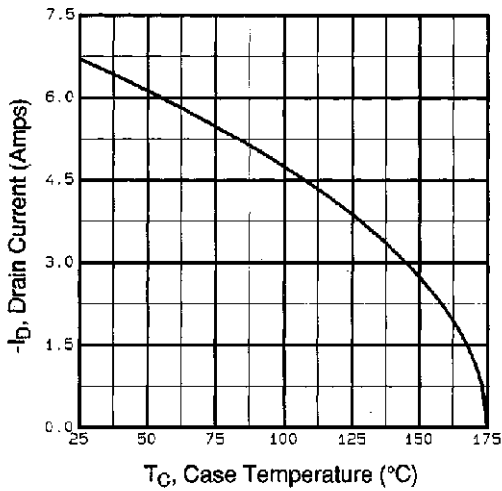
**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



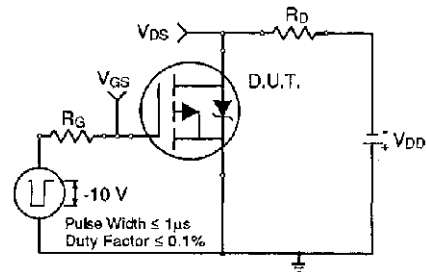
**Fig 7.** Typical Source-Drain Diode Forward Voltage



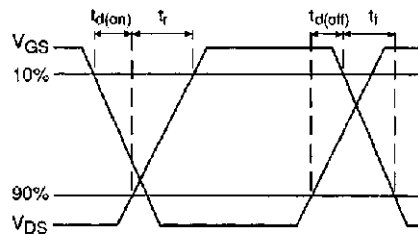
**Fig 8.** Maximum Safe Operating Area



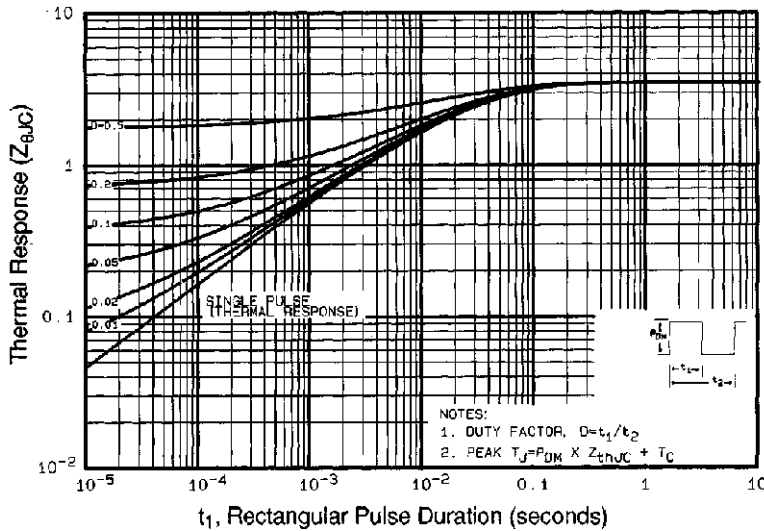
**Fig 9.** Maximum Drain Current Vs. Case Temperature



**Fig 10a.** Switching Time Test Circuit



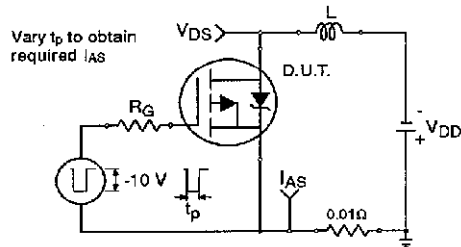
**Fig 10b.** Switching Time Waveforms



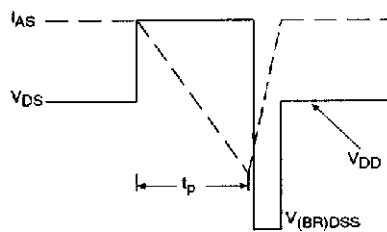
**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Case

# IRF9Z14PbF

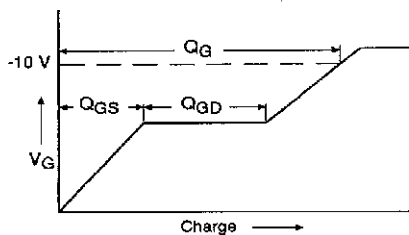
International  
**IR** Rectifier



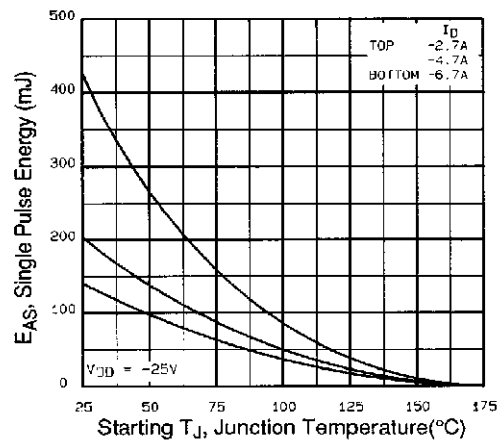
**Fig 12a.** Unclamped Inductive Test Circuit



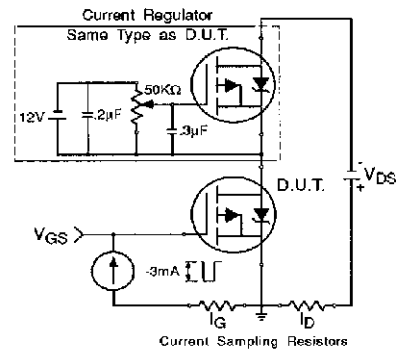
**Fig 12b.** Unclamped Inductive Waveforms



**Fig 13a.** Basic Gate Charge Waveform

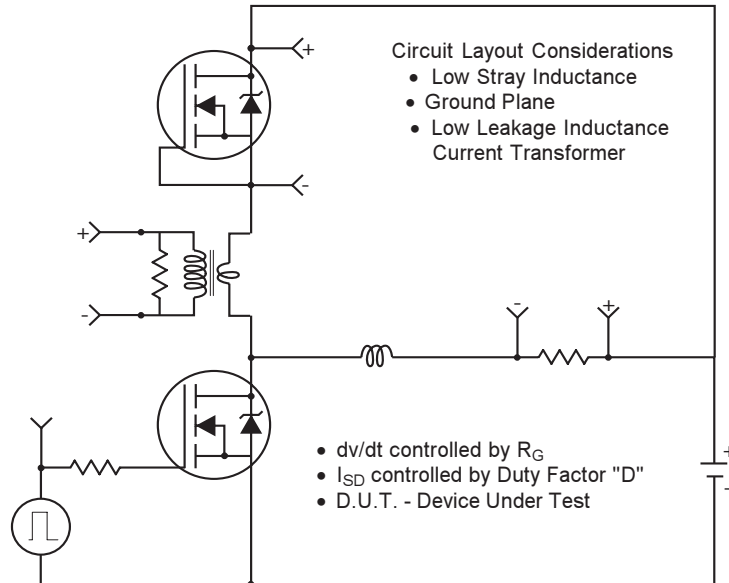


**Fig 12c.** Maximum Avalanche Energy Vs. Drain Current



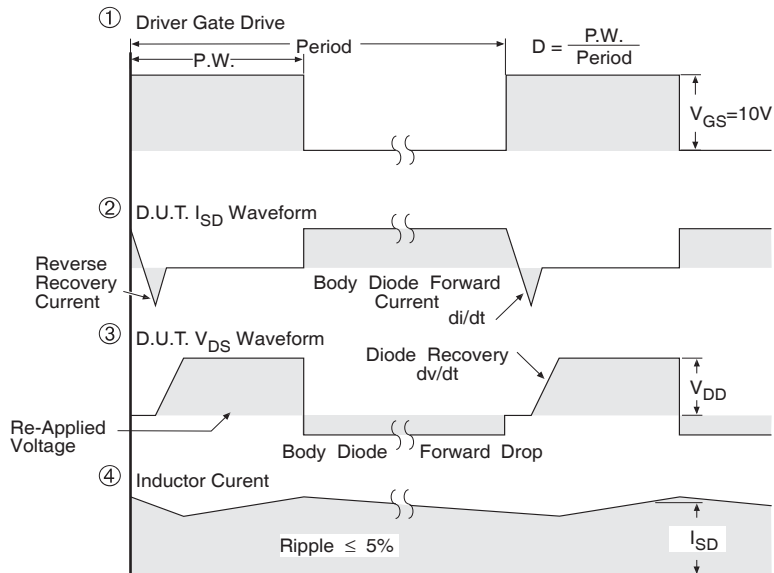
**Fig 13b.** Gate Charge Test Circuit

## Peak Diode Recovery dv/dt Test Circuit



\* Reverse Polarity for P-Channel

\*\* Use P-Channel Driver for P-Channel Measurements



\*\*\*  $V_{GS} = 5.0V$  for Logic Level and 3V Drive Devices

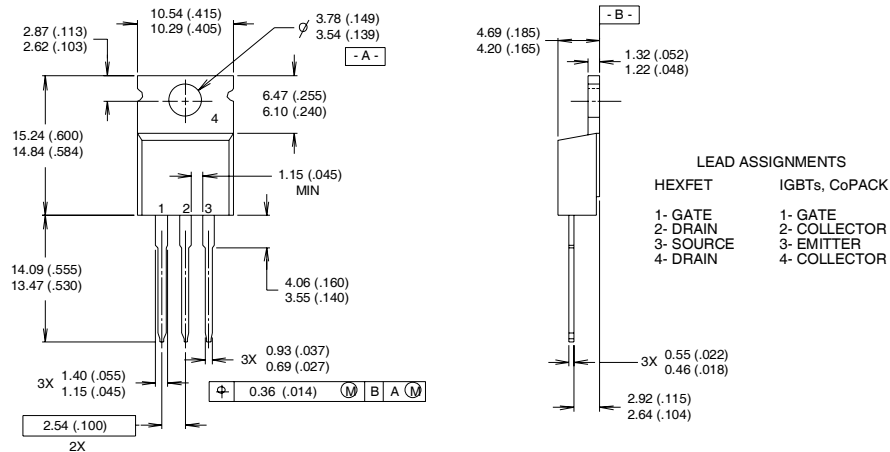
**Fig. 14** For N and P Channel HEXFETS

# IRF9Z14PbF



## TO-220AB Package Outline

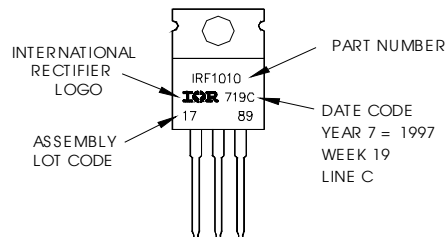
Dimensions are shown in millimeters (inches)



- NOTES:
- 1 DIMENSIONING & TOLERANCING PER ANSI Y14.5M, 1982.
  - 2 CONTROLLING DIMENSION : INCH
  - 3 OUTLINE CONFORMS TO JEDEC OUTLINE TO-220AB.
  - 4 HEATSINK & LEAD MEASUREMENTS DO NOT INCLUDE BURRS.

## TO-220AB Part Marking Information

EXAMPLE: THIS IS AN IRF1010  
 LOT CODE 1789  
 ASSEMBLED ON WW 19, 1997  
 IN THE ASSEMBLY LINE "C"  
**Note:** "P" in assembly line position indicates "Lead-Free"



Data and specifications subject to change without notice.



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 08/04

Document Number: 91088

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